

ABSTRACT

Disclosed is a film carrier tape for mounting electronic part comprising an insulating film and a wiring pattern which is made of a conductive metal and is provided on the surface of the insulating film, wherein an undercoating layer containing nickel as a main constituent is formed on at least a part of the surface of the wiring pattern made of a conductive metal, an intermediate layer containing palladium as a main constituent is formed on the surface of the undercoating layer, a surface layer containing gold as a main constituent is formed on the surface of the intermediate layer, and the average thickness of the intermediate layer containing palladium as a main constituent is not more than 0.04 μm . According to the present invention, a film carrier tape for mounting electronic part, in which the wire bonding strength to the bonding pad (connecting terminal) and the peel strength of the solder ball to the ball pad are high and the variability range of these strengths is small, is provided.